Attorney Docket No.: C330.104.101

## **DECLARATION FOR UNITED STATES PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR DIODE LASER SPECTROMETER ARRANGEMENT AND METHOD the specification of which is attached hereto unless the following is checked:

| [] The sp                                   | ecification was file                     | ed onas United State   | es Application Number  |
|---|--|--|--|
|   |  | eviewed and understand the cims, as amended by any amendment               | ontents of the above-identified ent referred to above.   |
|   | ge the duty to dis-<br>e of Federal Regu |  | ial to patentability as defined in   |
| foreign application any foreign application | ation(s) for patent                      | or inventor's certificate listed bel<br>nt or inventor's certificate havin | States Code, § 119(a)-(d) of any. low and have also identified belowing a filing date before that of the |
| Prior Foreign Application(s)                |  |  | Priority Claimed   |
| 0208100.8                                   | GB                                       | 09 April 2002  | Yes  |
| (Number)                                    | (Country)                                | (Day/Month/Year Filed)   | (Yes/No)   |
| (Number)                                    | (Country)                                | (Day/Month/Year Filed)   | (Yes/No)   |
|   | n the benefit und plication(s) listed b  |  | e, § 119(e) of any United States   |
| (Application Number)                        |  |  |  |
| (Application Number)                        |  | (Filing Date)  |  |

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application(s) in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

| PCT/GB03/0l 510      | 08 April 2003 | Pending                               |
|----------------------|---------------|---------------------------------------|
| (Application Number) |               | (Status-patented, pending, abandoned) |

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I hereby appoint the following attorneys and/or agents with full powers (including the power of appointment, substitution, and revocation) to prosecute this application and any division, continuation, continuation-in-part, reexamination, or reissue thereof, and to transact all business in the Patent and Trademark Office connected therewith:

## **CUSTOMER NO. 025281**

The undersigned hereby authorizes the U.S. attorney(s) and/or agent(s) named above to accept and follow instructions from University of Strathclyde as to any action to be taken in the United States Patent and Trademark Office regarding this application without direct communication between the US. attorney(s) and/or agent(s) and the undersigned. In the event of a change in the persons from whom instructions may be taken, the U.S. attorney(s) or agent(s) name above will be so notified by the undersigned.

Please address all correspondence and telephone calls to William M. Hienz at:

CUSTOMER NO. 025281

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

|   | Nigel Langford Full name of first inventor (given name, family name)                 | 5 Octher 2004                        |
|---|--|--------------------------------------|
|   | Inventor's signature   | Date                                 |
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|   | Geoffrey Duxbury Full name of second inventor (given name, family name)              |                                      |
| ) | Inventor's signature   | Date 5 Ochlee 2004                   |

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[X] Additional inventor is named on the attached sheet.

Residence (City and either State or Foreign Country)

Attorney Docket No.: 330.104.101

| Erwan Normand   |             |  |  |  |  |
|---|-------------|--|--|--|--|
| Full name of third inventor (given name, family name)       |             |  |  |  |  |
| fland,  |             |  |  |  |  |
|   | 25/10/08    |  |  |  |  |
| Inventor's signature Date                                   | e 05/10/09  |  |  |  |  |
| Classes Great Britain F.B.A                                 | 4 D % 1     |  |  |  |  |
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